

MARKED-UP VERSION OF AMENDED CLAIMS

- - 3. (amended) A wiring substrate according to claim [1 or] 2,

in which the low-elasticity underlayer is made of a material having a Young's modulus of less than 1 GPa measured at a room temperature (20 to 30 °C) and a Young's modulus of 10 MPa or less measured at 150 °C.

4. (amended) A wiring substrate according to [anyone of] claim[s 1 to] 3, in which the rerouted wiring is covered with a solder resist layer, and the solder resist layer is made of a resist material having a Young's modulus of less than 1 GPa measured at a room temperature (20 to 30 °C) and a Young's modulus of 10 MPa or less measured at 150 °C.

5. (amended) A wiring substrate according to [anyone of] claim[s 1 to] 4, in which the low-elasticity underlayer extends between the base material of the wiring substrate and the external-connection terminal, the low-elasticity underlayer in the region of the electronic-part mounting pad and the rerouted wiring has a thickness of 50 μm or more, and the low-elasticity underlayer in the region of the external-connection terminal has a thickness of 10 μm or less.

6. (amended) A wiring substrate according to [anyone of] claim[s 1 to] 5, in which the rerouted wiring is formed in a nonlinear pattern, at least, between the electronic-part mounting pad and the external-connection terminal.

9. (amended) A method of manufacturing a wiring substrate according to claim [7 or] 8, which comprises the steps of:

forming a low-elasticity underlayer from a material having a Young's modulus of less than 1 GPa measured at a room temperature (20 to 30 °C) and a Young's modulus of 10 MPa or less measured at 150 °C, on the base material of the wiring substrate;

forming a through-hole that extends from the upper surface of the low-elasticity underlayer to the rerouted wiring on the base material located at the lower surface of the low-elasticity underlayer, at a predetermined position of the low-elasticity underlayer; and

forming, by plating, a connection via-hole in the through-hole, the electronic-part mounting pad, and the rerouted wiring. - -